



To the Director of the U.S. Patents and Trademark

103468421

all documents or copy thereof.

1. Name of conveying party(ies):
Young Deuk KIM

Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
Name: HYNIX SEMICONDUCTOR INC.

Internal Address:

3. Nature of conveyance/Execution Date(s):
Execution Date November 26, 2007

- Assignment Merger
- Security Agreement Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other

Street Address: San 136-1, Ami-ri, Bubal-eup, Icheo
Gyeonggi-do 467-701, Korea

City:

State:

Zip Code:

Additional name(s) & Address(es) attached?

Yes No

4. Application number(s) or patent number(s):

This document is being filed together with a new application

A. Patent Application Number(s):

B. ~~12/05/2007~~ ~~ENGINEER~~ ~~00000047~~ ~~11987759~~
04 FC:0021 40.00 OP

Additional numbers attached?

Yes No

5. Name and address of to whom correspondence concerning document should be mailed:

Name: Mr. Ernest F. Chapman

6. Total number of applications and registrations involved: 1

7. Total fee (37 CFR 3.41): \$40

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed (Please charge deficiency to deposit account)
- None required (government interest not affecting title)

Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.

8. Payment Information

Street Address: 901 New York Avenue, NW

a. Credit Card Last 4 Numbers _____
Expiration Date _____

City: Washington, D.C.

b. Deposit Account No.: 06-0916

State: Zip: 20001-4413

Authorized User Name _____

8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Ernest F. Chapman
Reg. No. 25,961

Signature

December 4, 2007
Date

Total number of pages including cover sheet, attachments and documents: 3

JOINT INVENTION
(U.S. Rights Only)

ASSIGNMENT

WHEREAS, We, the below named inventors, (hereinafter referred to as assignors, have made an invention entitled:

SEMICONDUCTOR DEVICE AND METHOD OF FABRICATING THE SAME

for which we executed an application for United States Letters Patent
concurrently herewith or on or filed an application for United
States Letters Patent on (Application No.);
and

WHEREAS, Hynix Semiconductor Inc., a corporation of Republic of Korea, whose post office address is San 136-1, Ami-ri, Bubal-eup, Icheon-si, Gyeonggi-do 467-701, Korea. (hereinafter referred to as assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, we, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and we hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY further covenant and agree that we will, without further consideration, communicate with assignee, its successors and assigns, any facts known to us respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, WE HEREBY authorize and request the attorneys we have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. , filed) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, we have hereunto set our hands.

First Assignor

Assignor: Young Deuk KIM

Address: #103-206 Godam Dormitory, Godam-dong,
Icheon-si, Gyeonggi-do 467-140, Korea

Citizenship: Republic of Korea

Signature: 

Date: November 26, 2007

Second Assignor

Assignor: _____

Address: _____

Citizenship: _____

Signature: _____

Date: _____

Third Assignor

Assignor: _____

Address: _____

Citizenship: _____

Signature: _____

Date: _____